

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1-11. Canceled.

12. (Currently Amended) A transponder comprising:

-a chip ~~(5)~~ having contact pads; ~~(7)~~ and

at least two coupling elements ~~(8)~~, ~~which are~~ conductively connected with the contact pads ~~(7)~~, ~~characterized in that~~ wherein:

the coupling elements ~~(8)~~ are touch-free relative to each other and formed in a self-supported as well as free-standing way and are essentially extended parallel to ~~the a~~ plane of the chip plane;

~~the a~~ total mounting height of the transponder corresponds essentially to ~~the a~~ mounting height of the chip ~~(5)~~; and

the coupling elements ~~(8)~~ ~~are in~~ have a geometry and size so as to be configurable adapted for acting-use as a dipole antenna or for use as a plate capacitor in conjunction with an evaluation unit ~~as a plate capacitor.~~

13. (Currently Amended) The transponder of claim 12, ~~characterized in that~~ wherein the connection of the coupling elements ~~(8)~~ with the contact pads ~~(7)~~ is performed on ~~the a~~ wafer.

14. (Currently Amended) The transponder of claim 12, ~~characterized in that~~ wherein the coupling elements ~~(8)~~ ~~formed as a dipole antenna~~ are formed in a meandrous way.

15. (Currently Amended) The transponder of claim 12, ~~characterized in that wherein the coupling elements (8) formed as a dipole antenna are adapted for operation at~~ has a working frequency of ~~more than 2.45~~ at least 2.45 GHz ~~or for operation at a working frequency of at least 24.125 GHz.~~

16. (Currently Amended) The transponder of claim 14, ~~characterized in that wherein the connection of the coupling elements (8) with the contact pads (7) is performed on the~~ a wafer.

17. (Currently Amended) The transponder of claim 15, ~~characterized in that wherein the connection of the coupling elements (8) with the contact pads (7) is performed on the~~ a wafer.

18. (Currently Amended) The transponder of claim 15, ~~characterized in that wherein the coupling elements (8) formed as a dipole antenna are formed in a meandrous way.~~

19. (Currently Amended) The transponder of claim 18, ~~characterized in that wherein the connection of the coupling elements (8) with the contact pads (7) is performed on the~~ a wafer.

20. (Currently Amended) A: transponder comprising:  
a chip ~~(5)~~ having a contact pad ~~(7)~~; and  
a coupling element ~~(8)~~, ~~which is conductively connected with the contact pad (7),~~  
~~characterized in that~~ wherein:

the coupling element ~~(8)~~ is formed in a self-supported as well as free-standing way and is essentially extended parallel to a plane of the chip ~~plane~~;

~~the~~ a total mounting height of the transponder corresponds essentially to ~~the~~ a mounting height of the chip ~~(5)~~; and

the coupling element (8) is configured in geometry and size ~~adapted as a plate capacitor for acting use~~ in conjunction with an evaluation unit ~~as a plate capacitor~~.

21. (Currently Amended) The transponder of claim 20, ~~characterized in that~~ wherein the connection of the coupling element (8) with the contact pad (7) is performed on ~~the~~ a wafer.

22-29. Canceled.

30. (New) The transponder of claim 12 wherein the dipole antenna has a working frequency of at least 24.125 GHz.

31. (New) The transponder of claim 30 wherein the dipole antenna has a meandrous configuration.

32. (New) A transponder comprising:  
a chip having at least two contact pads; and  
at least two coupling elements, each coupling element self-supporting and free-standing with respect to the other and each coupling element electrically connected to a respective contact pad on the chip, wherein the at least two coupling elements are configured as a dipole extending parallel to a plane of the chip and a mounting height of the transponder is approximately a mounting height of the chip.

33. (New) The transponder of claim 32 wherein the at least two coupling elements are connected to the respective contact pad on a wafer level.

34. (New) The transponder of claim 32 wherein the at least two coupling elements have a meandrous configuration.

35. (New) The transponder of claim 32 wherein the dipole has a working frequency of at least 2.45 GHz.

36. (New) The transponder of claim 32 wherein the dipole has a working frequency of at least 24.125 GHz.

37. (New) The transponder of claim 32 wherein the at least two coupling elements:

are connected to the respective contact pad on a wafer level; and  
have a meandrous configuration.

38. (New) The transponder of claim 37 wherein the dipole has a working frequency of at least 24.125 GHz.

39. (New) The transponder of claim 37 wherein the dipole has a working frequency of at least 2.45 GHz.